Power MOSFET 22 Amps, 60 Volts, Logic Level

N-Channel TO-220 and D²PAK

Designed for low voltage, high speed switching applications in power supplies, converters and power motor controls and bridge circuits.

Typical Applications

- Power Supplies
- Converters
- Power Motor Controls
- Bridge Circuits

MAXIMUM RATINGS (T_J = 25°C unless otherwise noted)

Rating	Symbol	Value	Unit
Drain-to-Source Voltage	V_{DSS}	60	Vdc
Drain–to–Gate Voltage (R _{GS} = 10 MΩ)	V_{DGR}	60	Vdc
Gate-to-Source Voltage			Vdc
Continuous	V_{GS}	±10	
– Non–Repetitive (t _p ≤10 ms)	V_{GS}	±20	
Drain Current			
Continuous @ T_A = 25°C	I _D	22	Adc
- Continuous @ T _A = 100°C	I _D	10	
– Single Pulse (t _p ≤10 μs)	I _{DM}	66	Apk
Total Power Dissipation @ T _A = 25°C	P_{D}	60	W
Derate above 25°C		0.4	W/°C
Operating and Storage Temperature Range	T _J , T _{stg}	-55 to	°C
		+175	
Single Pulse Drain-to-Source Avalanche	E _{AS}	72	mJ
Energy – Starting $T_J = 25^{\circ}C$			
$(V_{DD} = 50 \text{ Vdc}, V_{GS} = 5.0 \text{ Vdc}, L = 1.0 \text{ mH}$			
$I_{L(pk)} = 12 \text{ A}, V_{DS} = 60 \text{ Vdc}, R_G = 25 \Omega$			
Thermal Resistance			°C/W
Junction—to—Case	$R_{\theta JC}$	2.5	
– Junction–to–Ambient	$R_{\theta JA}$	62.5	
Maximum Lead Temperature for Soldering	TL	260	°C
Purposes, 1/8" from case for 10 seconds			

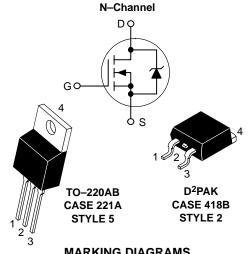


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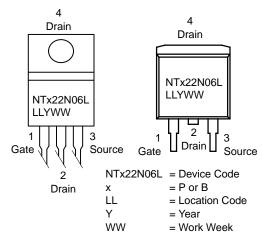
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22 AMPERES 60 VOLTS

 $R_{DS(on)} = 65 \text{ m}\Omega$



MARKING DIAGRAMS & PIN ASSIGNMENTS



ORDERING INFORMATION

Device	Package	Shipping
NTP22N06L	TO-220AB	50 Units/Rail
NTB22N06L	D ² PAK	50 Units/Rail
NTB22N06LT4	D ² PAK	800/Tape & Reel

ELECTRICAL CHARACTERISTICS (T_{.I} = 25°C unless otherwise noted)

	Symbol	Min	Тур	Max	Unit	
OFF CHARACTERISTICS						
Drain-to-Source Breakdown ($V_{GS} = 0 \text{ Vdc}$, $I_D = 250 \mu\text{A}$) Temperature Coefficient (Pos	V _{(BR)DSS}	60 -	68.2 81	_ _	Vdc mV/°C	
Zero Gate Voltage Drain Cur $(V_{DS} = 60 \text{ Vdc}, V_{GS} = 0 \text{ Vd})$ $(V_{DS} = 60 \text{ Vdc}, V_{GS} = 0 \text{ Vd})$	I _{DSS}	_ _	_ _	1.0 10	μAdc	
Gate-Body Leakage Current	I _{GSS}	-	-	±100	nAdc	
ON CHARACTERISTICS (Not	e 1.)					
Gate Threshold Voltage (Not $(V_{DS} = V_{GS}, I_D = 250 \mu Add)$ Threshold Temperature Coef	V _{GS(th)}	1.0	1.79 5.0	2.0	Vdc mV/°C	
Static Drain-to-Source On-F (V _{GS} = 5.0 Vdc, I _D = 11 Ad	R _{DS(on)}	-	57	65	mΩ	
Static Drain—to—Source On—V $(V_{GS} = 5.0 \text{ Vdc}, I_D = 22 \text{ Ac})$ $(V_{GS} = 5.0 \text{ Vdc}, I_D = 11 \text{ Ad})$	V _{DS(on)}	_ _	1.4 1.17	1.7 -	Vdc	
Forward Transconductance (9FS	_	14.6	ı	mhos	
OYNAMIC CHARACTERISTIC	es					
Input Capacitance	0.00	C _{iss}	-	490	690	pF
Output Capacitance	$(V_{DS} = 25 \text{ Vdc}, V_{GS} = 0 \text{ Vdc}, $ f = 1.0 MHz)	C _{oss}	-	167	230	
Transfer Capacitance	,	C _{rss}	_	56	80	
SWITCHING CHARACTERIST	FICS (Note 2.)					
Turn-On Delay Time		t _{d(on)}	_	10	20	ns
Rise Time	$(V_{DD} = 30 \text{ Vdc}, I_D = 22 \text{ Adc},$	t _r	_	115	230	
Turn-Off Delay Time	$V_{GS} = 5.0 \text{ Vdc}, R_G = 9.1 \Omega) \text{ (Note 1.)}$	t _{d(off)}	_	21	40	
Fall Time		t _f	_	56	120	
Gate Charge	(V _{DS} = 48 Vdc, I _D = 22 Adc, V _{GS} = 5.0 Vdc) (Note 1.)	Q _T	-	10.4	20	nC
		Q ₁	-	2.5	_	
		Q_2	_	7.0	-	
SOURCE-DRAIN DIODE CHA	ARACTERISTICS					
Forward On–Voltage	$(I_S = 22 \text{ Adc, } V_{GS} = 0 \text{ Vdc) (Note 1.)}$ $(I_S = 22 \text{ Adc, } V_{GS} = 0 \text{ Vdc, } T_J = 150^{\circ}\text{C})$	V _{SD}	- -	1.03 0.98	1.2 –	Vdc
Reverse Recovery Time	(I _S = 22 Adc, V _{GS} = 0 Vdc, dI _S /dt = 100 A/μs) (Note 1.)	t _{rr}	-	42	1	ns
		t _a	-	26	_	
		t _b	-	16	_	
Reverse Recovery Stored Charge		Q_{RR}	-	0.060	-	μС

^{1.} Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 2%.

^{2.} Switching characteristics are independent of operating junction temperatures.

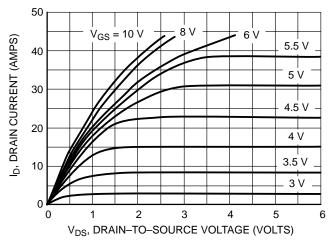


Figure 1. On-Region Characteristics

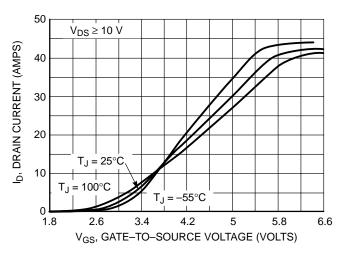


Figure 2. Transfer Characteristics

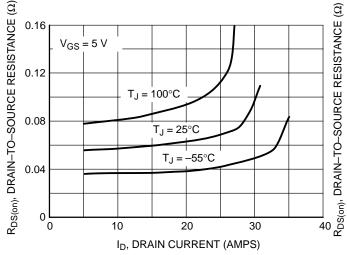


Figure 3. On–Resistance versus Gate–to–Source Voltage

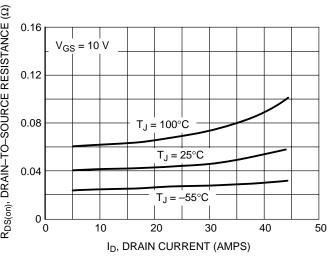


Figure 4. On–Resistance versus Drain Current and Gate Voltage

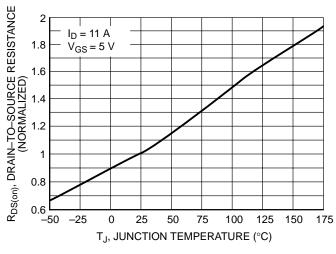


Figure 5. On–Resistance Variation with Temperature

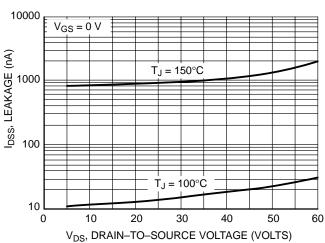


Figure 6. Drain-to-Source Leakage Current versus Voltage

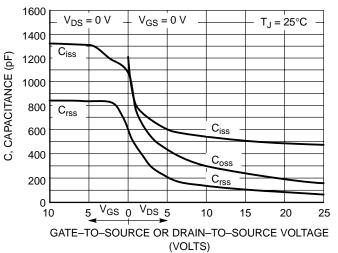


Figure 7. Capacitance Variation

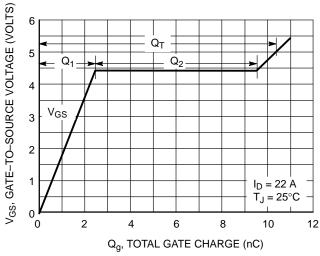


Figure 8. Gate-to-Source and Drain-to-Source Voltage versus Total Charge

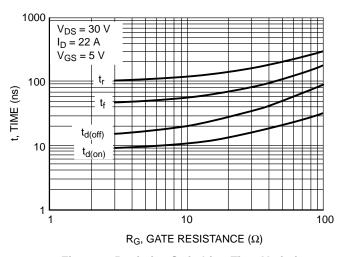


Figure 9. Resistive Switching Time Variation versus Gate Resistance

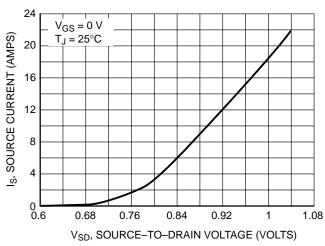


Figure 10. Diode Forward Voltage versus
Current

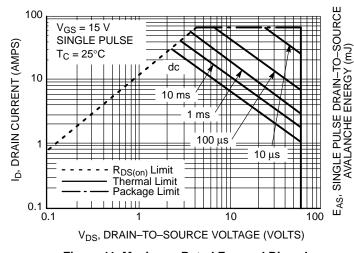


Figure 11. Maximum Rated Forward Biased Safe Operating Area

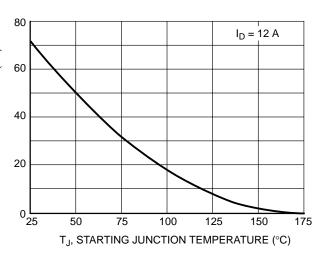


Figure 12. Maximum Avalanche Energy versus Starting Junction Temperature

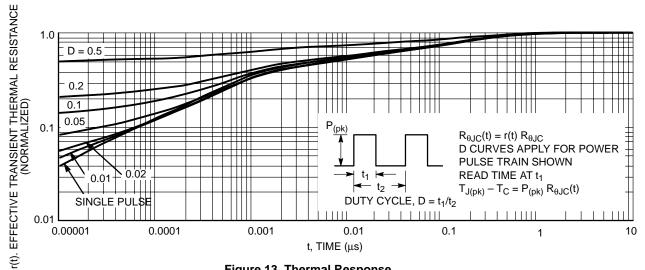


Figure 13. Thermal Response

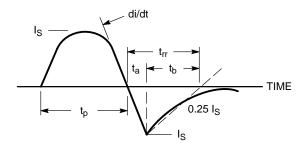
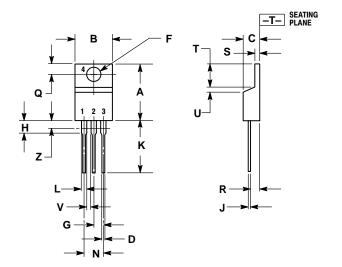


Figure 14. Diode Reverse Recovery Waveform

PACKAGE DIMENSIONS

TO-220 THREE-LEAD TO-220AB

CASE 221A-09 **ISSUE AA**



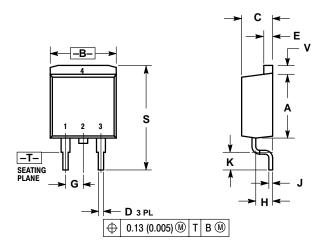
- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. DIMENSION Z DEFINES A ZONE WHERE ALL BODY AND LEAD IRREGULARITIES ARE ALLOWED.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
Α	0.570	0.620	14.48	15.75
В	0.380	0.405	9.66	10.28
C	0.160	0.190	4.07	4.82
D	0.025	0.035	0.64	0.88
F	0.142	0.147	3.61	3.73
G	0.095	0.105	2.42	2.66
Н	0.110	0.155	2.80	3.93
J	0.018	0.025	0.46	0.64
K	0.500	0.562	12.70	14.27
L	0.045	0.060	1.15	1.52
N	0.190	0.210	4.83	5.33
Q	0.100	0.120	2.54	3.04
R	0.080	0.110	2.04	2.79
S	0.045	0.055	1.15	1.39
Т	0.235	0.255	5.97	6.47
U	0.000	0.050	0.00	1.27
٧	0.045		1.15	
Z		0.080		2.04

STYLE 5: PIN 1. GATE 2. DRAIN

PACKAGE DIMENSIONS

D²PAK CASE 418B-03 ISSUE D



- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
Α	0.340	0.380	8.64	9.65
В	0.380	0.405	9.65	10.29
С	0.160	0.190	4.06	4.83
D	0.020	0.035	0.51	0.89
Е	0.045	0.055	1.14	1.40
G	0.100 BSC		2.54 BSC	
Н	0.080	0.110	2.03	2.79
J	0.018	0.025	0.46	0.64
K	0.090	0.110	2.29	2.79
S	0.575	0.625	14.60	15.88
٧	0.045	0.055	1.14	1.40

- STYLE 2: PIN 1. GATE 2. DRAIN 3. SOURCE 4. DRAIN

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